
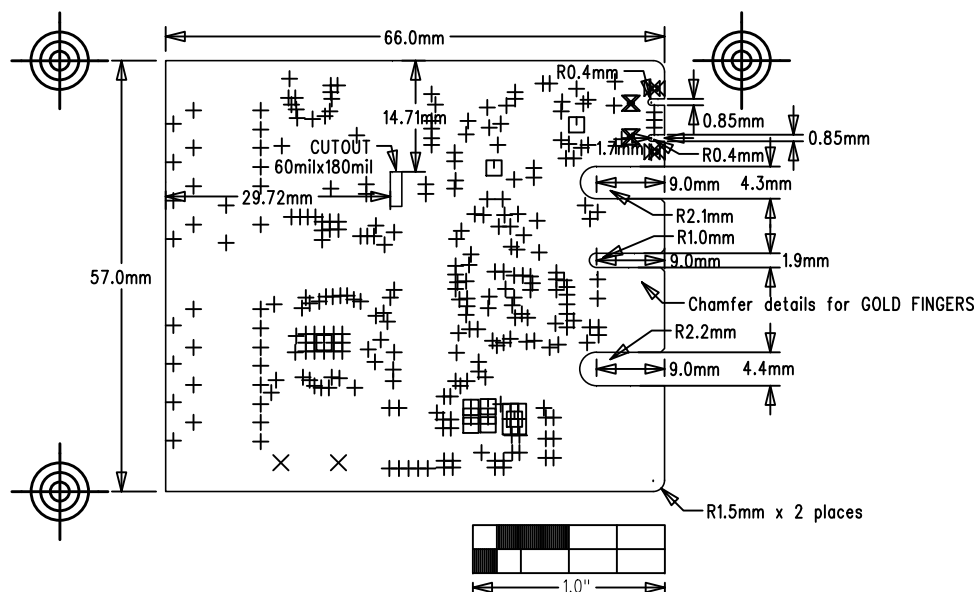
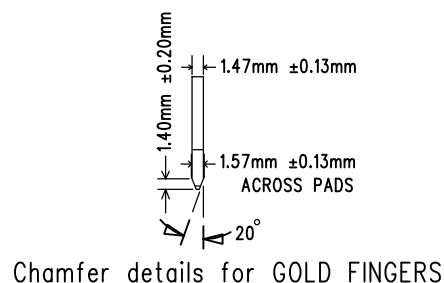


MAXREFDES64# uPLC IO Card - DI Board	
P/N: EPCBREFDES64	REV A
 maxim integrated™	
LAYER DRILL & MECHANICALS	
DATE:	ALL UNITS ARE IN 0.001"

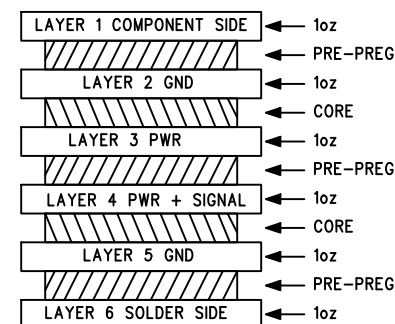


SIZE	QTY	SYM	PLATED	TOL
12	273	+	YES	+/-3.0
63	2	×	YES	+/-3.0
20	14	□	YES	+/-3.0
19.69 x 33.46	2	⊗	YES	+/-3.0
23.62 x 49.21	2	⊗	YES	+/-3.0



NOTES: UNLESS OTHERWISE SPECIFIED

- FABRICATE USING PROVIDED GERBER FILES PER LATEST REVISION OF IPC-A-600 UNLESS OTHERWISE NOTED.
- MATERIAL: RoHS COMPLIANT FR-408 OR SIMILAR LAMINATE MATERIAL WITH $T_g \geq 170$ AND COMPATIBLE WITH LEAD-FREE SOLDERING PROCESS.
- BOARD DIMENSIONS: 2.598"x2.244" (66mmx57mm) ± 0.010 ".
BOARD THICKNESS: 0.058" ± 0.005 " (1.47mm ± 0.13 mm).
- LAYERS: 6. SEE LAYER STACKUP CHART BELOW.
- MINIMUM TRACE/SPACING: 10 MILS/7.5 MILS.
- COPPER CLAD FINISH: 1oz MINIMUM ON OUTER LAYERS AND 1oz ON INNER LAYERS.
- SURFACE MOUNT PADS: 540.
- SOLDERMASK: GREEN LPI SMOBC.
- LEGENDS: WHITE, DOUBLE-SIDED, NON-CONDUCTIVE EPOXY INK OR EQUIVALENT.
CLIPPED ALL LEGENDS FROM EXPOSED METAL.
- PLATING: MUST BE LEAD FREE AND RoHS COMPLIANT.
- FINISH: VENDOR SHOULD USE THE MOST ECONOMICAL LEAD FREE AND RoHS COMPLIANT PROCESS AVAILABLE OR AS SPECIFIED IN PURCHASE ORDER.
GOLD FINGERS: 30 MICRO INCHES HARD GOLD OVER 250 MICRO INCHES NICKEL.
IMMERSION GOLD: REST OF BOARD AREA.
- VENDOR LOGO & DATE CODE IN INK ON BOTTOM SIDE ONLY. DATE CODE FORMAT MUST BE YYWW ONLY.
- THRU HOLES: 0.001" MIN.
- TOLERANCES:
PLATED-THRU HOLES: ± 0.003 "
PATTERN-TO-PATTERN: ± 0.005 "
LEGEND TO LEGEND: ± 0.007 "
SOLDERMASK TO PATTERN: ± 0.005 ".



CROSS SECTION DETAIL